



RE900-01

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for TSOP I 28, 40, 48, 60 (0.40 mm)
- Hole diameter 1.00 mm
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- Size: 29.29 x 43.64 mm

Modul-No.	Type	Pitch	Pin	Size (mm)
RE900-01	TSOP I	0.400 mm	28, 40, 48, 60	12.00 x 18.00